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# **FQS4900**

# **Dual N & P-Channel, Logic Level MOSFET**

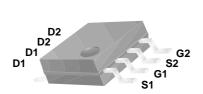
### **General Description**

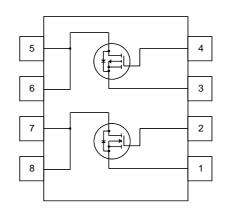
These dual N and P-channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. This device is well suited for high interface in telephone sets.

#### **Features**

- N-Channel 1.3A, 60V,  $R_{DS(on)}$  = 0.55  $\Omega$  @  $V_{GS}$  = 10 V  $\begin{array}{c} \text{R}_{DS(on)} = 0.65~\Omega \quad @ \text{V}_{GS} = 5~\text{V} \\ \text{P-Channel -0.3A, -300V, } \text{R}_{DS(on)} = 15.5~\Omega \quad @ \text{V}_{GS} = -10~\text{V} \\ \text{R}_{DS(on)} = 16~\Omega \quad @ \text{V}_{GS} = -5~\text{V} \\ \end{array}$  • Low gate charge ( typical N-Channel 1.6 nC)
- (typical P-Channel 3.6 nC)
- · Fast switching
- · Improved dv/dt capability





# Absolute Maximum Ratings T<sub>A</sub> = 25°C unless otherwise noted

Symbol	Parameter		N-Channel	P-Channel	Units
$V_{DSS}$	Drain-Source Voltage		60	-300	V
I <sub>D</sub>	Drain Current - Continuous (T <sub>A</sub> = 25°C)		1.3	-0.3	Α
	- Continuous (T <sub>A</sub> = 70°C)		0.82	-0.19	Α
I <sub>DM</sub>	Drain Curent - Pulsed	(Note 1)	5.2	-1.2	Α
V <sub>GSS</sub>	Gate-Source Voltage		± 20		V
dv/dt	Peak Diode Recovery dv/dt	(Note 2)	7.0	4.5	V/ns
P <sub>D</sub>	Power Dissipation (T <sub>A</sub> = 25°C)		2.0		W
	$(T_A = 70^{\circ}C)$		1.3		W
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150		°C

### **Thermal Characteristics**

Symbol	Parameter	Тур	Max	Units
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	-	62.5	°C/W

Symbol	Parameter	Test Conditions	Type	Min	Тур	Max	Units
Off Cha	aracteristics						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	N-Ch	60			V
DOO		$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	P-Ch	-300			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V				1	μА
		V <sub>DS</sub> = 48 V, T <sub>C</sub> = 55°C	N-Ch			10	μA
		V <sub>DS</sub> = -300 V, V <sub>GS</sub> = 0 V	- 0			-1	μΑ
		V <sub>DS</sub> = -240 V, T <sub>C</sub> = 55°C	P-Ch			-10	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 20 V, V <sub>DS</sub> = 0 V	All			100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = -20 V, V <sub>DS</sub> = 0 V	All			-100	nA
On Cha	racteristics		- 1	I		11	
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = 4V, I_{D} = 20 \text{ mA}$	N-Ch	1.0		1.95	V
00(11)	- care in carrein carries	$V_{DS} = 4V, I_{D} = -20 \text{ mA}$	P-Ch	-1.0		-1.95	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 0.65 A			0.39	0.55	Ω
DO(OII)		V <sub>GS</sub> = 5 V, I <sub>D</sub> = 0.65 A	N-Ch		0.46	0.65	Ω
		V <sub>GS</sub> = -10 V, I <sub>D</sub> = -0.15 A			11.2	15.5	Ω
		V <sub>GS</sub> = -5 V, I <sub>D</sub> = -0.15 A	P-CH		11.4	16	Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 0.65 A	N-CH		1.7		S
953	Torward Transcorradictarios	$V_{DS} = -10 \text{ V}, I_{D} = -0.15 \text{ A}$	P-CH		0.6		S
Switchi	ng Characteristics						
$t_{d(on)}$	Turn-On Delay Time	N-Channel	N-Ch		5.7	21	ns
_		$V_{DD} = 30 \text{ V}, I_{D} = 1.3 \text{ A},$	P-Ch		10	30	ns
t <sub>r</sub>	Turn-On Rise Time	$R_G = 25 \Omega$	N-Ch		21	50	ns
<b>+</b>		P-Channel	P-Ch N-Ch		25 11	60 32	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{DD} = -150 \text{ V}, I_D = -0.3 \text{ A},$	P-Ch		35	80	ns ns
t <sub>f</sub>		$R_G = 25 \Omega$	N-Ch		17	45	ns
1	Turn-Off Fall Time		P-Ch		47	105	ns
Qg	Total Gate Charge	N-Channel	N-Ch		1.6	2.1	nC
3	-	$V_{DS} = 48 \text{ V}, I_{D} = 1.3 \text{ A},$	P-Ch		3.6	4.7	nC
$Q_{gs}$	Gate-Source Charge	$V_{GS} = 5 V$	N-Ch		0.28		nC
		P-Channel	P-Ch		0.42		nC
$Q_{gd}$	Gate-Drain Charge	$V_{DS} = -240 \text{ V}, I_{D} = -0.3 \text{ A},$ $V_{GS} = -5 \text{ V}$	N-Ch		0.82		nC
		VGS3 V	P-Ch		2.1		nC
	ource Diode Characteristics a		1	I		I	T
I <sub>S</sub>	Maximum Continuous Drain-Source Did	ode Forward Current	N-Ch			1.3	A
		V -0VI 42A	P-Ch			-0.3	A
$V_{SD}$	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V, } I_{S} = 1.3 \text{ A}$	N-Ch			1.5	V
	- I I I I I I I I I I I I I I I I I I I	$V_{GS} = 0 \text{ V, } I_{S} = -0.3 \text{ A}$	P-Ch			-4.0	

- Notes: 1. Repetitive Rating : Pulse width limited by maximum junction temperature 3. Pulse Test : Pulse width  $\leq 300\mu s$ , Duty cycle  $\leq 2\%$  4. Essentially independent of operating temperature

# **Typical Characteristics: N-Channel**

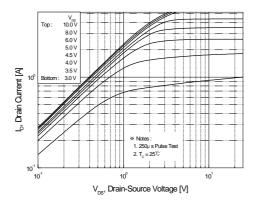


Figure 1. On-Region Characteristics

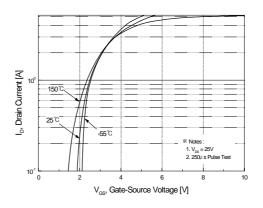


Figure 2. Transfer Characteristics

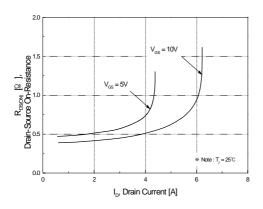


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

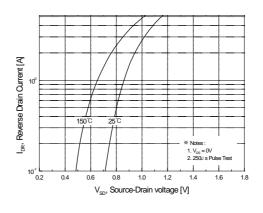


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

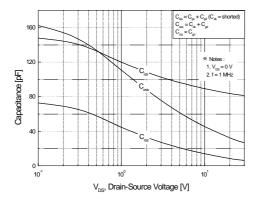


Figure 5. Capacitance Characteristics

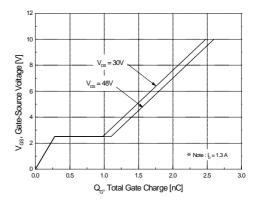


Figure 6. Gate Charge Characteristics

# **Typical Characteristics: N-Channel (Continued)**

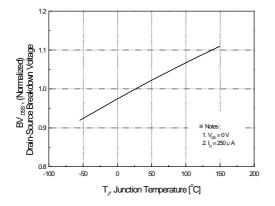
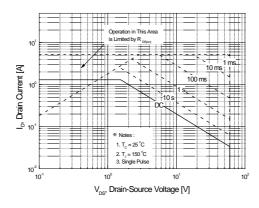


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



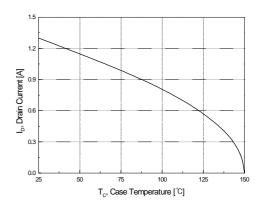


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

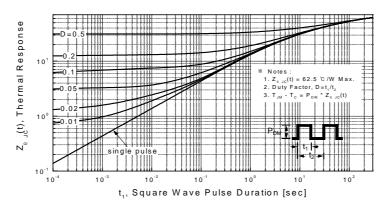


Figure 11. Transient Thermal Response Curve

# **Typical Characteristics: P-Channel** (Continued)

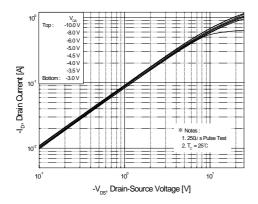


Figure 1. On-Region Characteristics

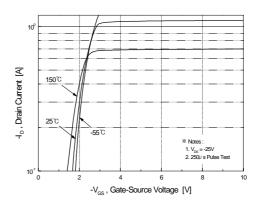


Figure 2. Transfer Characteristics

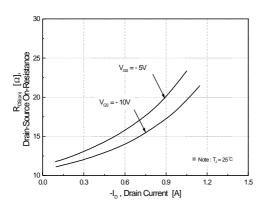


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

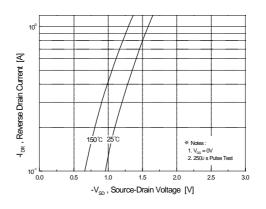


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

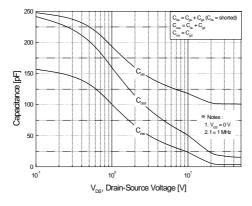


Figure 5. Capacitance Characteristics

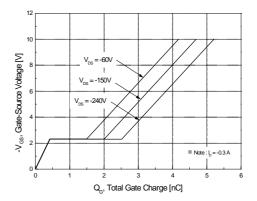


Figure 6. Gate Charge Characteristics

# **Typical Characteristics: P-Channel** (Continued)

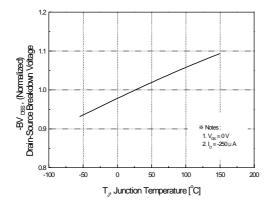


Figure 7. Breakdown Voltage Variation vs. Temperature

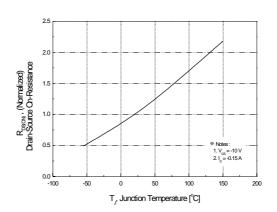


Figure 8. On-Resistance Variation vs. Temperature

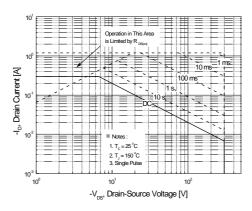


Figure 9. Maximum Safe Operating Area

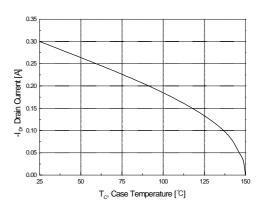


Figure 10. Maximum Drain Current vs. Case Temperature

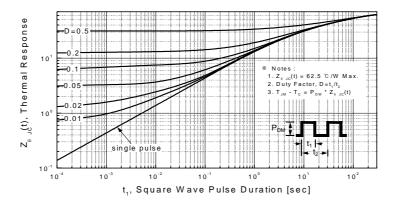
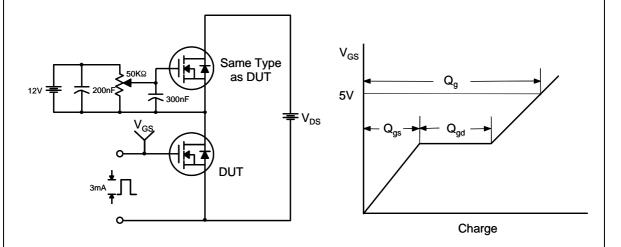
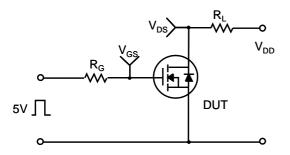


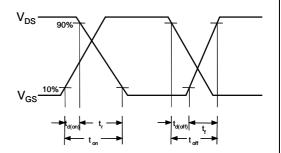
Figure 11. Transient Thermal Response Curve

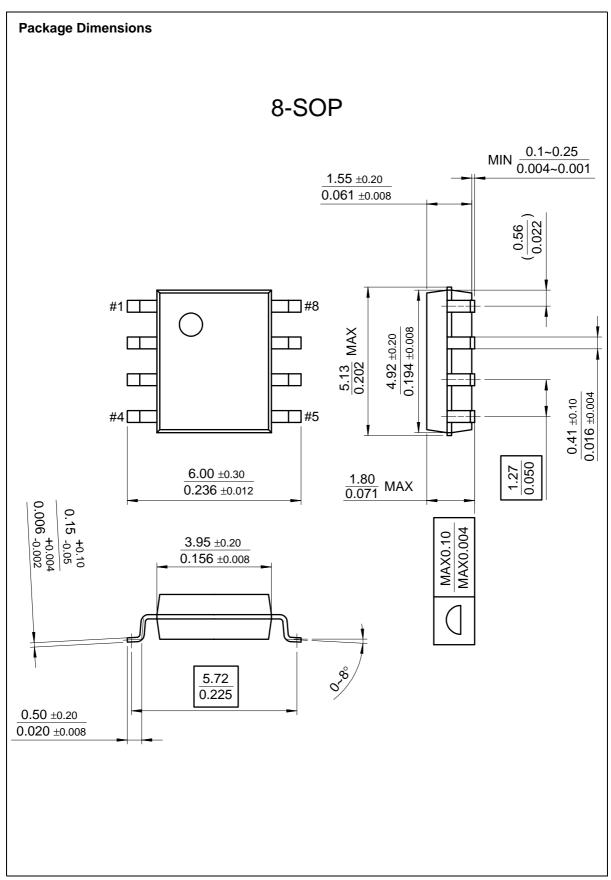
## **Gate Charge Test Circuit & Waveform**



## **Resistive Switching Test Circuit & Waveforms**







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